

TITLE: METHODS FOR FORMING ASSEMBLIES AND PACKAGES
THAT INCLUDE STACKED SEMICONDUCTOR DEVICES
SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL
INTERPOSED THEREBETWEEN

Inventor: J. Derderian
Docket No.: 2269-4817.3US

1/3

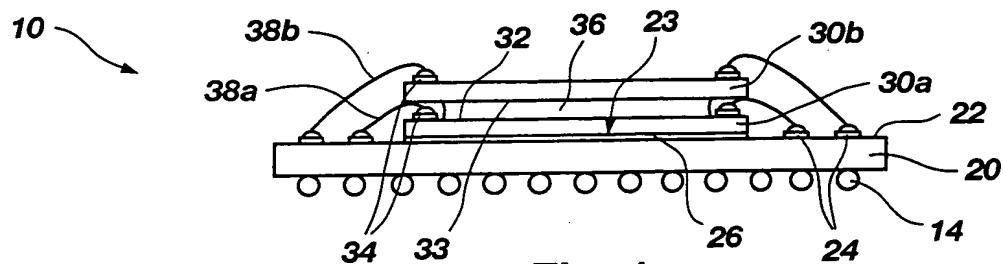


Fig. 1

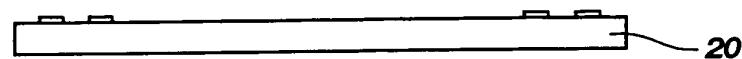


Fig. 2

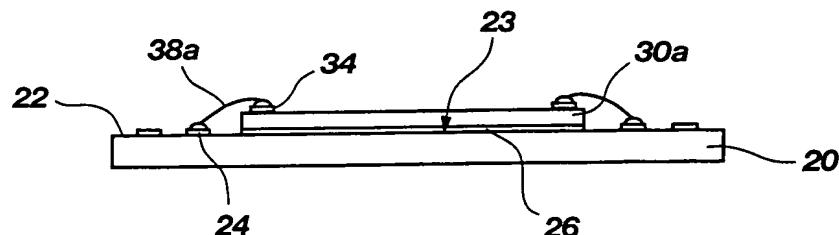


Fig. 3

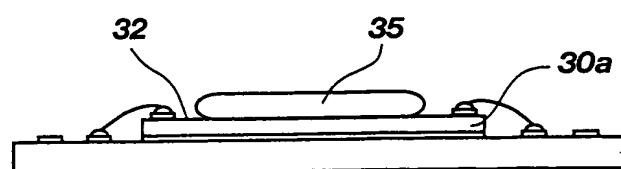


Fig. 4

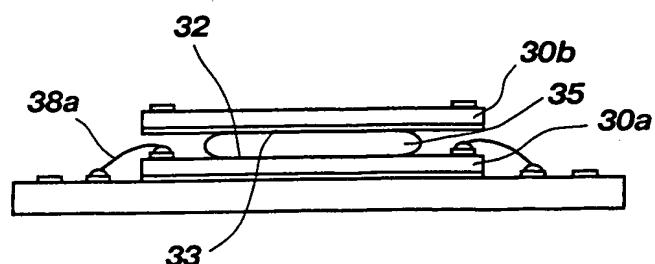


Fig. 5

TITLE: METHODS FOR FORMING ASSEMBLIES AND PACKAGES
THAT INCLUDE STACKED SEMICONDUCTOR DEVICES
SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL
INTERPOSED THEREBETWEEN

Inventor: J. Derderian
Docket No.: 2269-4817.3US

2/3

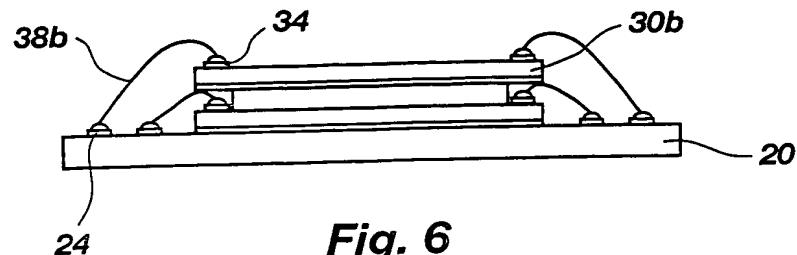


Fig. 6

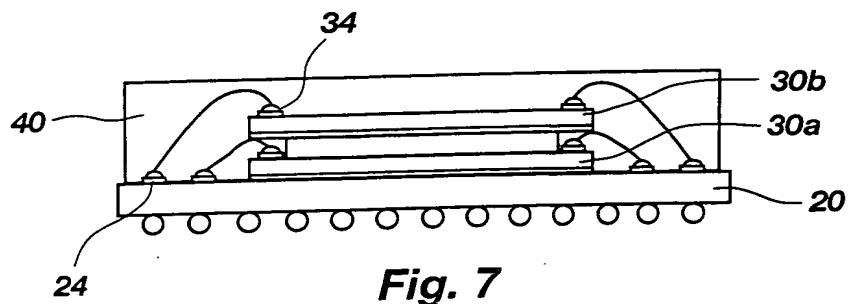


Fig. 7



Fig. 8

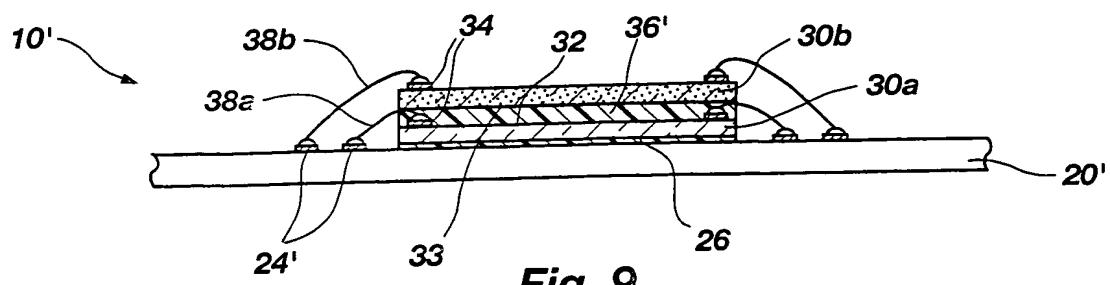


Fig. 9

TITLE: METHODS FOR FORMING ASSEMBLIES AND PACKAGES
THAT INCLUDE STACKED SEMICONDUCTOR DEVICES
SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL
INTERPOSED THEREBETWEEN

Inventor: J. Derderian
Docket No.: 2269-4817.3US

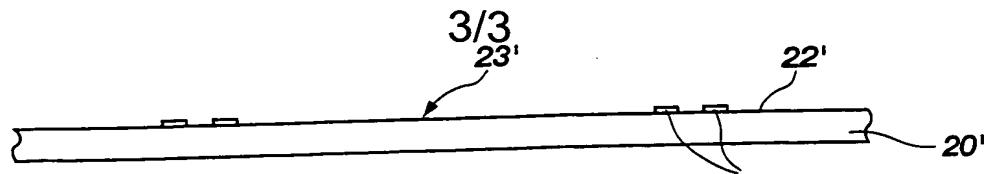


Fig. 10

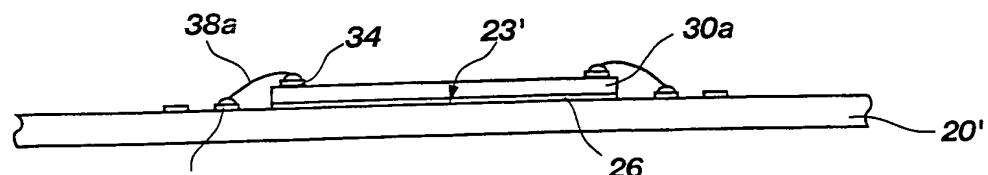


Fig. 11

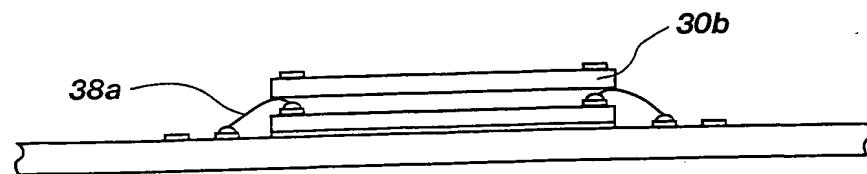


Fig. 12

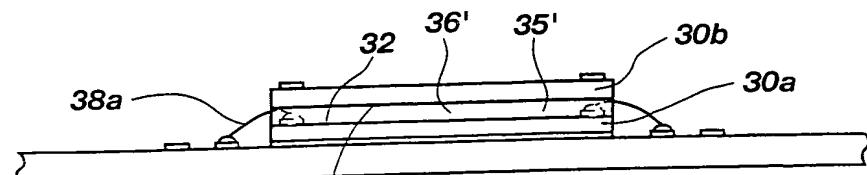


Fig. 13

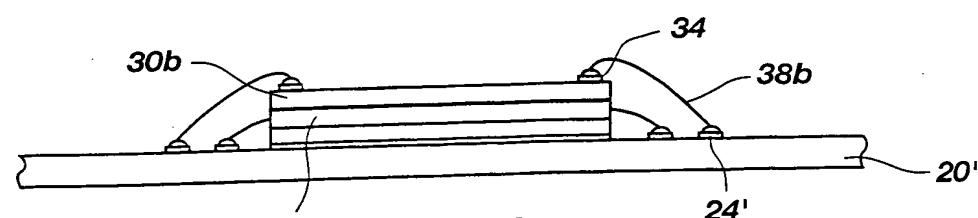


Fig. 14

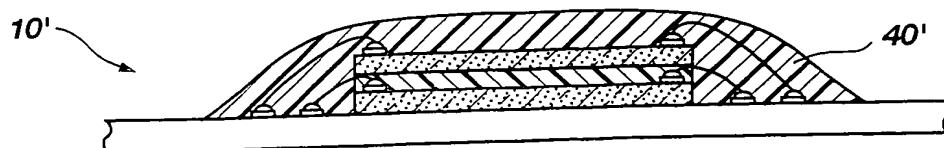


Fig. 15

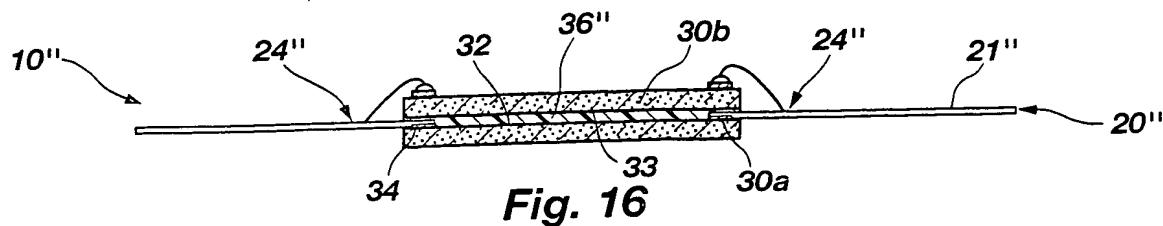


Fig. 16